CLEARFIL S\(^3\) BOND PLUS
High-tech and high speed for high performance

CLEARFIL S\(^3\) BOND PLUS is the one-step adhesive for direct restorations. It has been developed based on CLEARFIL S\(^3\) BOND technology, which reveals five years of clinical evidence. Etching, priming and bonding steps are completed with one-liquid, one-coat treatment.

The excellent bond strength to enamel and dentine of CLEARFIL S\(^3\) BOND PLUS marks a new standard among one-step adhesives, enabled by Kuraray’s innovative adhesive technology, which has been successful for more than 30 years. Its fast and simple application combined with its fluoride-releasing property makes CLEARFIL S\(^3\) BOND PLUS the ideal choice for all kinds of clinical situations, including paediatric therapy and core build-ups with the new CLEARFIL DC CORE PLUS. Furthermore, the system allows for precise and economic dosing.

The main benefit of using one-step adhesives is to reduce technical errors, thanks to a short application time and simple handling. The time-saving procedure makes CLEARFIL S\(^3\) BOND PLUS ready for immediate use in only three short steps: apply, air-dry, light-cure—all done in less than 30 seconds.

CLEARFIL S\(^3\) BOND PLUS is easy and comfortable to use because time-intensive work steps, such as shaking the bottle, exact mixing and application of several components, multiple layering and rubbing in on the tooth surface, are no longer necessary.

The high bond strength of CLEARFIL S\(^3\) BOND PLUS is the result of two Kuraray innovative technologies: the high performance initiator and the proven MDP monomer. The new high performance initiator for light-curing improves clinical performance by building up more active radicals than conventional initiators and making the bond more impervious to water thanks to the increased polymerisation ratio.

The integrated adhesive monomer MDP ensures a strong chemical bond to hydroxyapatite. In use for more than 25 years in successful products like PANAVIA F 2.0 and CLEARFIL SE BOND, the MDP monomer attains a high bond strength and reliable adhesive durability to tooth structure.

The stable interface between tooth and composite resin is furthermore ensured by Kuraray’s unique Molecular Dispersion Technology contained in CLEARFIL S\(^3\) BOND PLUS. The technology allows hydrophilic and hydrophobic components of the bond to be homogenously combined—constantly. Thus, there is no phase separation, resulting in the formation of a homogenous layer on the preparation surface. The bond, showing no water voids, excels through its excellent bond performance.

CLEARFIL S\(^3\) BOND PLUS is always ready to use and will have users persuaded of its durable high bond strength.

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